

Product / Process Change Notification



N° 2020-090-A

Dear Customer,

Please find attached our Infineon Technologies AG PCN:

Change of wafer diameter from 200mm to 300mm for modules with TRENCHSTOP™ 5 H5 IGBTs plus introduction of additional site for EC diodes

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **10 May 2021**
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:** 650V HighSpeed 5 IGBT modules;
please refer to affected product list 1_cip20090_a

► **Detailed Change Information:**

Subject: Change of wafer diameter from 200mm to 300mm for modules with TRENCHSTOP™ 5 H5 IGBTs plus introduction of additional site for EC diodes

Reason: Capacity extension and increasing security of supply for 650V HighSpeed 5 chips and emitter controlled diodes

Description:	<u>Old</u>	<u>New</u>
	<ul style="list-style-type: none">■ IGBT: 200mm■ Frontend site in Villach/Austria■ Emitter controlled diode Frontend site in Villach/Austria	<ul style="list-style-type: none">■ IGBT: 300mm■ Frontend site in Dresden/Germany■ Emitter controlled diode 200mm Frontend site in Villach/Austria and in Kulim/Malaysia

► **Product Identification:** During a transition period, a delivery with both variants is possible. The first DateCode of the new devices is going to be communicated.

► **Impact of Change:** No change in form, fit and function of the mentioned product

► **Attachments:** Affected product list 1_cip20090_a

► **Time Schedule:**

- Final qualification report: on request
- First samples available: on request
- Intended start of delivery: June 2021 or earlier after customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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plus introduction of additional site for EC diodes



Sales name	SP number	OPN	Package
DF100R07W1H5FP_B53	SP001629710	DF100R07W1H5FPB53BPSA2	AG-EASY1B
DF100R07W1H5FP_B54	SP001650156	DF100R07W1H5FPB54BPSA2	AG-EASY1B
DF80R07W1H5FP_B11	SP001781604	DF80R07W1H5FPB11BPSA1	AG-EASY1B
DF80R07W1H5FP_B50	SP005342696	DF80R07W1H5FPB50BPSA1	AG-EASY1B
DF80R07W1H5S8_B11	SP001899390	DF80R07W1H5S8B11BOMA1	AG-EASY1B
FS3L40R07W2H5F_B11	SP001713486	FS3L40R07W2H5FB11BOMA1	AG-EASY2B
FS3L40R07W2H5F_B67	SP003366126	FS3L40R07W2H5FB67BOMA1	AG-EASY2B
FB50R07W2E3_B23	SP005341840	FB50R07W2E3B23BOMA1	AG-EASY2B